

ABSTRACT OF THE DISCLOSURE

A fine electrode and wiring pattern with a good adhesive property is easily formed using a water-based solution easy to handle and small in
5 environmental load, thereby improving a stability of a manufacturing process of an image-forming apparatus in the case where the water-based solution is used in the manufacturing process. A base pattern is formed using a base pattern forming material for electrode
10 and wiring material absorption which is a water-based solution containing a water-soluble photosensitive resin component and a water-soluble metallic compound including rhodium, bismuth, ruthenium, vanadium, chromium, tin, lead, or silicon. An organic metallic
15 compound is absorbed in the base pattern and then baking is conducted to form electrodes and wirings.